查询MAX4684供应商

19-1977; Rev 3; 2/03

# 捷多邦,专业PCB打样工厂,24小时加急出货

# /N/IXI/N 0.5 $\Omega$ /0.8 $\Omega$ Low-Voltage, Dual SPDT Analog Switches in UCSP

## **General Description**

The MAX4684/MAX4685 low on-resistance (RON), lowvoltage, dual single-pole/double-throw (SPDT) analog switches operate from a single +1.8V to +5.5V supply. The MAX4684 features a  $0.5\Omega$  (max) R<sub>ON</sub> for its NC switch and a  $0.8\Omega$  (max) R<sub>ON</sub> for its NO switch at a +2.7V supply. The MAX4685 features a  $0.8\Omega$  max onresistance for both NO and NC switches at a +2.7V supply.

Both parts feature break-before-make switching action (2ns) with  $t_{ON}$  = 50ns and  $t_{OFF}$  = 40ns at +3V. The digital logic inputs are 1.8V logic-compatible with a +2.7V to +3.3V supply.

The MAX4684/MAX4685 are packaged in the chipscale package (UCSP)™, significantly reducing the required PC board area. The chip occupies only a 2.0mm × 1.50mm area. The 4 × 3 array of solder bumps are spaced with a 0.5mm bump pitch.

# **Applications**

Speaker Headset Switching

MP3 Players

Power Routing

Battery-Operated Equipment

**Relay Replacement** 

Audio and Video Signal Routing WWW.DZSC.COM

**Communications Circuits** 

PCMCIA Cards

**Cellular Phones** 

Modems

UCSP is a trademark of Maxim Integrated Products, Inc. Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

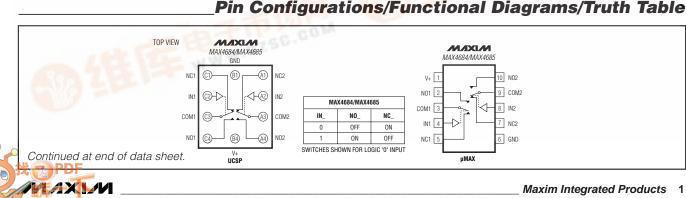
- 12-Bump, 0.5mm-Pitch UCSP
- NC Switch Ron 0.5Ω max (+2.7V Supply) (MAX4684)
  - 0.8Ω max (+2.7V Supply) (MAX4685)
- NO Switch Ron 0.8Ω max (+2.7V Supply)
- RON Match Between Channels **0.06**Ω (max)
- RON Flatness Over Signal Range **0.15**Ω (max)
- +1.8V to +5.5V Single-Supply Operation
- Rail-to-Rail<sup>®</sup> Signal Handling
- 1.8V Logic Compatibility
- Low Crosstalk: -68dB (100kHz)
- High Off-Isolation: -64dB (100kHz)
- THD: 0.03%
- 50nA (max) Supply Current
- Low Leakage Currents 1nA (max) at  $T_A = +25^{\circ}C$

# **Ordering Information**

PART	TEMP RANGE	PIN/BUMP- PACKAGE	TOP MARK
MAX4684EBC	-40°C to +85°C	12 UCSP*	AAF
MAX4684ETB	-40°C to +85°C	10 Thin QFN (3 × 3)	AAG
MAX4684EUB	-40°C to +85°C	10 µMAX	_
MAX4685EBC	-40°C to +85°C	12 UCSP*	AAG
MAX4685ETB	-40°C to +85°C	10 Thin QFN (3 × 3)	AAH
MAX4685EUB	-40°C to +85°C	10 µMAX	—

Note: Requires special solder temperature profile describing the Absolute Maximum Ratings section.

\*UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and environment. Refer to the UCSP Reliability Notice in the UCSP Reliability section of this data sheet for more information.



For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at

**Features** 

## **ABSOLUTE MAXIMUM RATINGS**

(All Voltages Referenced to GND)

ν+, IN	0.3V to +6V
COM_, NO_, NC_ (Note1)	0.3V to (V+ + 0.3V)
Continuous Current NO_, NC_, COM	±300mA
Peak Current NO_, NC_, COM_	
(pulsed at 1ms, 50% duty cycle)	±400mA
Peak Current NO_, NC_, COM_	
(pulsed at 1ms, 10% duty cycle)	±500mA

Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
12-Bump UCSP (derate 11.4mW/°C above +70°C)909mW
10-Pin µMAX (derate 5.6mW/°C above +70°C)444mW
Operating Temperature Ranges40°C to +85°C
Storage Temperature Range65°C to +150°C
Lead Temperature (soldering, 10s)+300°C
Bump Temperature (soldering) (Note 2)
Infared (15s)+220°C
Vapor Phase (60s)+215°C

Note 1: Signals on NO\_, NC\_, and COM\_ exceeding V+ or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.

**Note 2:** This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry-standard specification, JEDEC 020A, paragraph 7.6, Table 3 for IR/VPR and Convection reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# ELECTRICAL CHARACTERISTICS—+3V SUPPLY

 $(V + = +2.7V \text{ to } +3.3V, V_{IH} = +1.4V, V_{IL} = +0.5V, T_A = T_{MIN} \text{ to } T_{MAX}$ , unless otherwise noted. Typical values are at +3V and +25°C.) (Notes 3, 9, 10)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS		
ANALOG SWITCH				•					
Analog Signal Range	V <sub>NO</sub> , V <sub>NC</sub> , V <sub>COM</sub>			E	0		V+	V	
			MAX4684	+25°C		0.3	0.5	1	
NC_ On-Resistance	R <sub>ON(NC)</sub>	V+ = 2.7V; I <sub>COM</sub> = 100mA;	101/1/14004	E			0.5	Ω	
(Note 4)	FUN(NC)	$V_{NC} = 0$ to V+	MAX4685	+25°C		0.45	0.8	52	
			1010 074000	E			0.8		
NO_ On-Resistance	$V_{-}$ On-Resistance $V_{+} = 2.7V; I_{COM_{-}} = 100 \text{ mA};$		٩;	+25°C		0.45	0.8	Ω	
(Note 4)	Ron(no)	$V_{NO_{-}} = 0$ to V+	E			0.8	12		
On-Resistance Match Between Channels	ΔRon	V+ = 2.7V; I <sub>COM</sub> = 100mA;		+25°C			0.06	Ω	
(Notes 4, 5)		$V_{NO}$ or $V_{NC}$ = 1.5V	.5V				0.06		
NC_ On-Resistance	D	V+ = 2.7V; I <sub>COM</sub> = 100mA;	MAX4684	E			0.15	0	
Flatness (Note 6)	RFLAT (NC)	$V_{NC} = 0$ to V+	MAX4685	E			0.35	Ω	
NO_ On-Resistance Flatness (Note 6)	RFLAT (NO)	$V_{+} = 2.7V; I_{COM} = 100mA;$ $V_{NO_{-}} = 0 \text{ to } V_{+}$		E			0.35	Ω	
NO_ or NC_ Off-				+25°C	-1		1		
Leakage Current (Note 7)	I <sub>NO</sub> _(OFF) or I <sub>NC</sub> _(OFF)	V+ = 3.3V; V <sub>NO</sub> _ or V <sub>NC</sub> _ = 3V, 0.3V; V <sub>COM</sub> _ = 0.3V, 3V		E	-10		10	nA	
COM_ On-Leakage	e (crii	V+ = 3.3V; V <sub>NO</sub> or V <sub>NC</sub> = 3V, 0.3V, or floating; V <sub>COM</sub> = 3V, 0.3V, or floating		+25°C	-2		2		
Current (Note 7)	I <sub>COM</sub> (ON)			E	-20		20	nA	
DYNAMIC CHARACTE	RISTICS								
Turn On Time	tou	$V_{+} = 2.7V, V_{NO_{-}} \text{ or } V_{NC_{-}} = 1.5V;$ $R_{L} = 50\Omega; C_{L} = 35pF; Figure 2$		+25°C		30	50		
Turn-On Time	ton			E			60	ns	

# **0.5Ω/0.8Ω Low-Voltage, Dual SPDT** Analog Switches in UCSP

## ELECTRICAL CHARACTERISTICS—+3V SUPPLY (continued)

(V+ = +2.7V to +3.3V, V<sub>IH</sub> = +1.4V, V<sub>IL</sub> = +0.5V, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted. Typical values are at +3V and +25°C.) (Notes 3, 9, 10)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS	
Turn-Off Time	torr	$V_{+} = 2.7V, V_{NO}$ or $V_{NC} = 1.5V;$	+25°C		25	30	ns	
	toff	$R_L = 50\Omega$ ; $C_L = 35pF$ ; Figure 2	E			40	113	
Break-Before-Make Delay	<sup>t</sup> BBM	$V_{+} = 2.7V, V_{NO_{-}}, \text{ or } V_{NC_{-}} = 1.5V;$ $R_{L} = 50\Omega; C_{L} = 35\text{pF}; \text{ Figure } 3$	E 2 15			ns		
Charge Injection	Q	$COM_{-} = 0; R_{S} = 0; C_{L} = 1nF; Figure 4$	+25°C		200		рС	
Off-Isolation (Note 8)	V <sub>ISO</sub>	$C_L = 5pF; R_L = 50\Omega; f = 100kHz;$ $V_{COM_} = 1V_{RMS};$ Figure 5	+25°C		-64		dB	
Crosstalk	V <sub>CT</sub>	$C_L = 5pF; R_L = 50\Omega; f = 100kHz; +25^{\circ}C$ -68			dB			
Total Harmonic Distortion	THD	$R_L = 600\Omega$ , $IN_= 2Vp-p$ , $f = 20Hz$ to $20kHz$	+25°C		0.03		%	
NC_Off-Capacitance	C <sub>NC_(OFF)</sub>	f = 1MHz; Figure 6	+25°C		84		pF	
NO_Off-Capacitance	C <sub>NO_(OFF)</sub>	f = 1MHz; Figure 6	+25°C		37		pF	
NC_ On-Capacitance	C <sub>NC_(ON)</sub>	f = 1MHz; Figure 6	+25°C		190		pF	
NO_On-Capacitance	C <sub>NO_(ON)</sub>	f = 1MHz; Figure 6	+25°C		150		pF	
DIGITAL I/O								
Input Logic High	VIH		E	1.4			V	
Input Logic Low	VIL		E			0.5	V	
IN_ Input Leakage Current	I <sub>IN</sub>	$V_{IN-} = 0 \text{ or } V+$	E	-1		1	μΑ	
POWER SUPPLY								
Power-Supply Range	V+		E	1.8		5.5	V	
Supply Current (Note 4)	1+	$V_{+} = 5.5V; V_{IN_{-}} = 0 \text{ or } V_{+}$	+25°C	-50	0.04	50	nA	
		$\mathbf{v}_{1} = 0, 0, \mathbf{v}_{111} = 0, 0, \mathbf{v}_{111}$	E	-200		200	10.1	

MAX4684/MAX4685

**Note 3:** The algebraic convention used in this data sheet is where the most negative value is a minimum and the most positive value a maximum.

Note 4: Guaranteed by design.

**Note 5:**  $\Delta R_{ON} = R_{ON(MAX)} - R_{ON(MIN)}$ , between NC1 and NC2 or between NO1 and NO2.

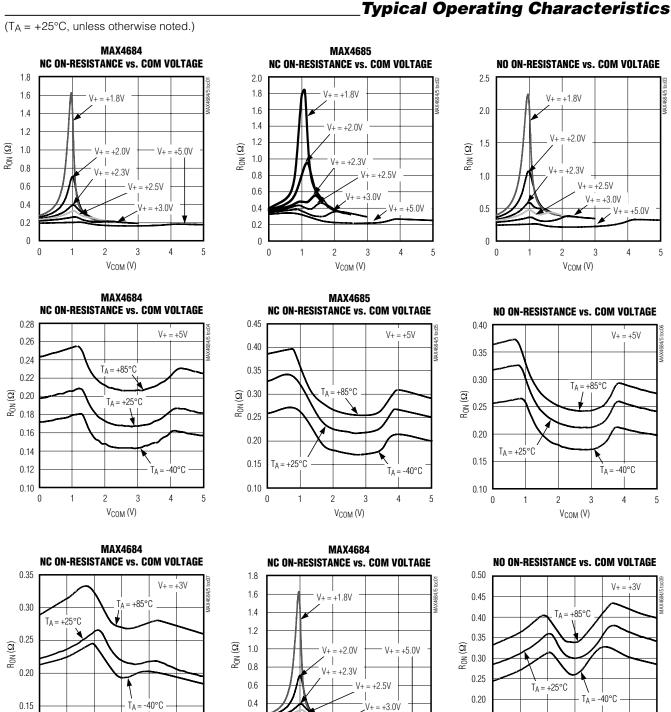
**Note 6:** Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.

Note 7: Leakage parameters are 100% tested at  $T_A = +85^{\circ}C$ , and guaranteed by correlation over rated temperature range.

**Note 8:** Off-isolation =  $20\log_{10} (V_{COM} / V_{NO}), V_{COM} = output, V_{NO} = input to off switch.$ 

**Note 9:** UCSP and QFN parts are 100% tested at +25°C only and guaranteed by design and correlation at the full hot-rated temperature.

Note 10: -40°C specifications are guaranteed by design.



0.15

0.10

0

0.5

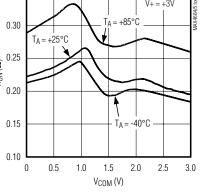
1.0

1.5

V<sub>COM</sub> (V)

2.0

2.5 3.0



0.2

0

0

1

3

V<sub>COM</sub> (V)

4

5

2

MAX4684/MAX4685

#### $(T_A = +25^{\circ}C, unless otherwise noted.)$ **TURN-ON/TURN-OFF TIMES TURN-ON/TURN-OFF TIMES** SUPPLY CURRENT vs. SUPPLY VOLTAGE vs. SUPPLY VOLTAGE vs. TEMPERATURE 50 80 100 $V_{+} = +3V$ 45 70 40 80 60 35 tом 50 t∩⊾ 30 60 tow/tore (ns) ton/toFF (ns) 40 25 torr 20 40 30 15 20 tore 20 10 10 5 0 0 0 2.3 2.8 3.8 4.3 4.8 5.3 2 3 4 5 1.8 3.3 -40 -15 10 35 60 0 1 6 TEMPERATURE (°C) V<sub>SUPPLY</sub> (V) V<sub>SUPPLY</sub> (V) MAX4684 LOGIC THRESHOLD VOLTAGE **ON/OFF-LEAKAGE CURRENT** vs. SUPPLY VOLTAGE vs. TEMPERATURE **CHARGE INJECTION vs. COM VOLTAGE** 2.0 1000 300 200 **DN/OFF-LEAKAGE CURRENT (pA)** 1.5 V<sub>IN</sub> RISING 100 100 0 (ja) 0 -100 1.0 VIN FALLING ICOM(ON) -200 10 0.5 -300 -400 ICOM(OFF) 0 -500 1 0 1 2 3 4 5 6 -40 4 -15 10 35 60 85 0 1 2 3 5 6 VSUPPLY (V) TEMPERATURE (°C) V<sub>COM</sub> (V) MAX4685 **ON/OFF-LEAKAGE CURRENT** TOTAL HARMONIC DISTORTION FREQUENCY RESPONSE (µMAX) vs. TEMPERATURE **PLUS NOISE vs. FREQUENCY** 1000 0 0.1 ON-RESPONSE -20 100 -40 OFF-ISOLATION THD + N (%) LOSS (dB) ICOM(ON) -60 I IAT22 10 -80 ICOM(OFF) -100 0.01 -120 1 10 100 10k 100k

# **Typical Operating Characteristics (continued)**

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MAX4684/MAX4685

10

TEMPERATURE (°C)

35

60

85

0.01

0.1

1

FREQUENCY (MHz)

10

100

0.001

SUPPLY CURRENT (pA)

-OGIC THRESHOLD VOLTAGE (V)

ON/OFF-LEAKAGE CURRENT (pA)

-40

-15

1k

FREQUENCY (Hz)

### **Pin Description**

PIN		PIN	FUNCTION			
NAME	UCSP	μΜΑΧ	FUNCTION			
NC_	A1, C1	5, 7	Analog Switch—Normally Closed Terminal			
IN_	A2, C2	4, 8	Digital Control Input			
COM_	A3, C3	3, 9	Analog Switch—Common Terminal			
NO_	A4, C4	2, 10	Analog Switch—Normally Open Terminal			
V+	B4	1	Positive Supply Voltage Input			
GND	B1	6	Ground			

## \_Detailed Description

The MAX4684/MAX4685 are low on-resistance, low-voltage, dual SPDT analog switches that operate from a +1.8V to +5.5V supply. The devices are fully specified for nominal 3V applications. The MAX4684/MAX4685 have break-before-make switching and fast switching speeds ( $t_{ON} = 50$ ns max,  $t_{OFF} = 40$ ns max).

The MAX4684 offers asymmetrical normally closed (NC) and normally open (NO) R<sub>ON</sub> for applications that require asymmetrical loads (examples include speaker headsets and internal speakers). The part features a 0.5 $\Omega$  max R<sub>ON</sub> for its NC switch and a 0.8 $\Omega$  max RON for its NO switch at the 2.7V supply. The MAX4685 features a 0.8 $\Omega$  max on-resistance for both NO and NC switches at the +2.7V supply.

## **Applications Information**

#### **Digital Control Inputs**

The MAX4684/MAX4685 logic inputs accept up to +5.5V regardless of supply voltage. For example, with a +3.3V supply, IN\_ may be driven low to GND and high to 5.5V. Driving IN\_ rail-to-rail minimizes power consumption. Logic levels for a +1.8V supply are 0.5V (low) and 1.4V (high).

#### **Analog Signal Levels**

Analog signals that range over the entire supply voltage (V+ to GND) are passed with very little change in on-resistance (see *Typical Operating Characteristics*). The switches are bidirectional, so the NO\_, NC\_, and COM\_ pins can be either inputs or outputs.

#### Power-Supply Sequencing and Overvoltage Protection

Caution: Do not exceed the absolute maximum ratings because stresses beyond the listed ratings may cause permanent damage to devices.

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V+ before applying analog signals, especially if the analog signal is not current limited. If this sequencing is not possible, and if the analog inputs are not current limited to <20mA, add a small signal diode (D1) as shown in Figure 1. Adding a protection diode reduces the analog range to a diode drop (about 0.7V) below V+ (for D1). R<sub>ON</sub> increases slightly at low supply voltages. Maximum supply voltage (V+) must not exceed +6V. Protection diode D1 also protects against some overvoltage situations. No damage will result on Figure 1's circuit if the supply voltage is below the absolute maximum rating applied to an analog signal pin.

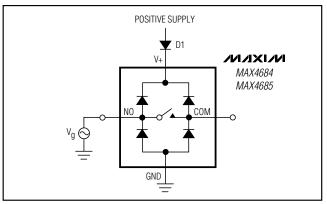


Figure 1. Overvoltage Protection Using Two External Blocking Diodes



#### **UCSP Package Consideration**

For general UCSP package information and PC layout considerations, please refer to the Maxim Application Note (Wafer-Level Ultra-Chip-Board-Scale Package).

### UCSP Reliability

The chip-scale package (UCSP) represents a unique packaging form factor that may not perform equally to a packaged product through traditional mechanical reliability tests. UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering use of a UCSP package. Performance through Operating Life Test and Moisture Resistance remains uncompromised as it is primarily determined by the wafer-fabrication process. Mechanical stress performance is a greater consideration for a UCSP package. UCSPs are attached through direct solder contact to the user's PC board, foregoing the inherent stress relief of a packaged product lead frame. Solder joint contact integrity must be considered. Information on Maxim's qualification plan, test data, and recommendations are detailed in the UCSP application note, which can be found on Maxim's website at www.maxim-ic.com.

### **Chip Information**

TRANSISTOR COUNT: 198

## Test Circuits/Timing Diagrams

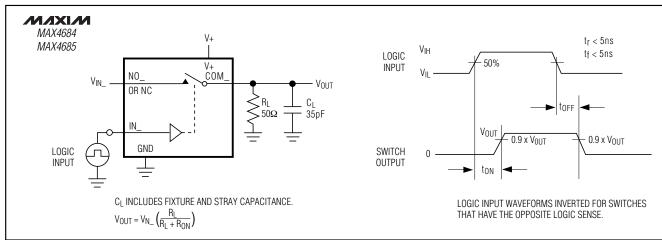


Figure 2. Switching Time

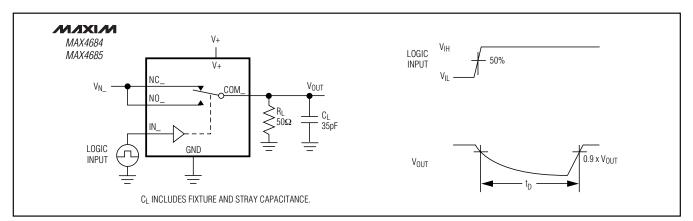


Figure 3. Break-Before-Make Interval

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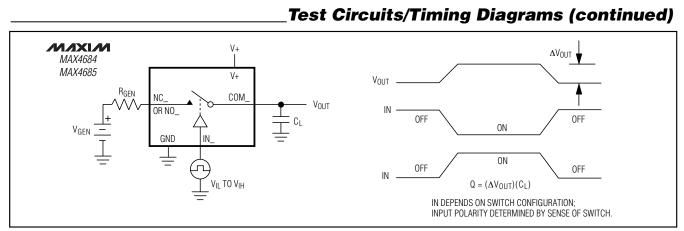


Figure 4. Charge Injection

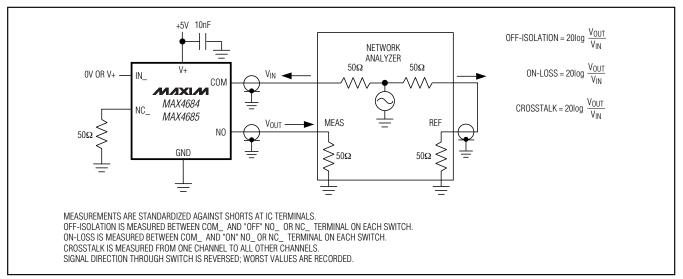


Figure 5. On-Loss, Off-Isolation, and Crosstalk

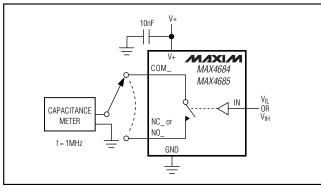
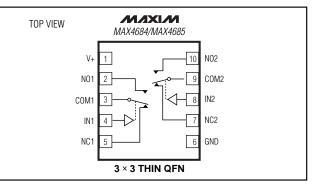


Figure 6. Channel Off/On-Capacitance

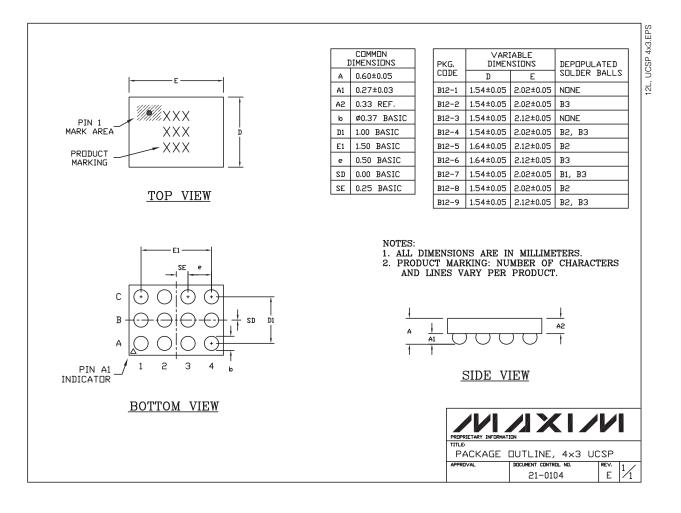
# \_Pin Configurations (continued)



# **0.5**Ω/**0.8**Ω Low-Voltage, Dual SPDT Analog Switches in UCSP

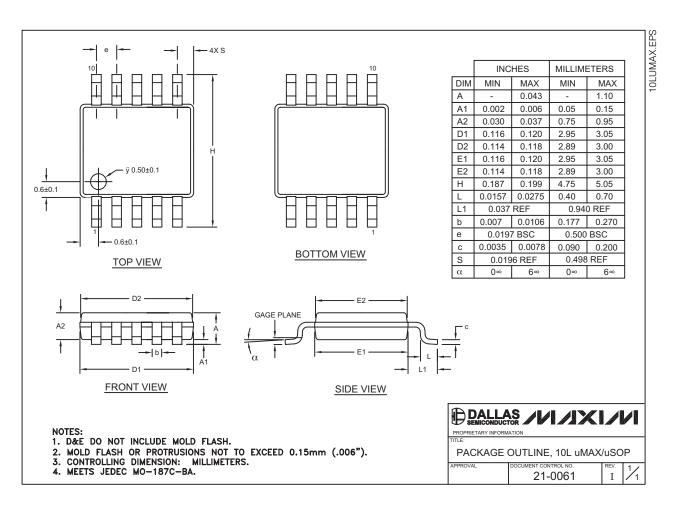
## **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



## \_Package Information (continued)

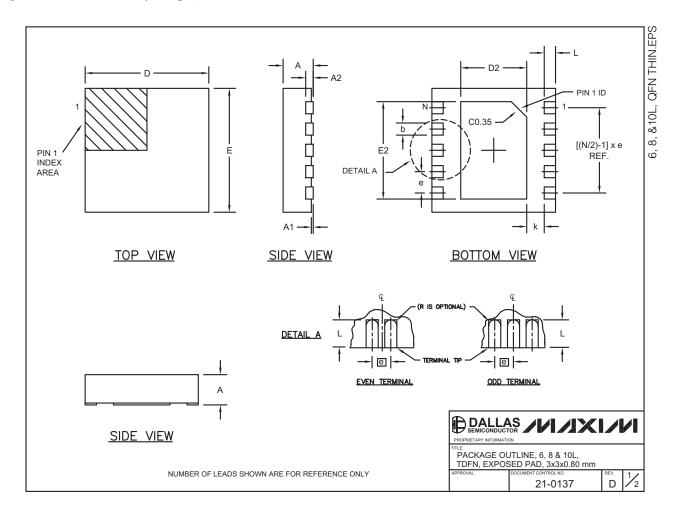
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# **0.5**Ω/0.8Ω Low-Voltage, Dual SPDT Analog Switches in UCSP

# Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <u>www.maxim-ic.com/packages</u>.)



## Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)

COMMC	COMMON DIMENSIONS				
SYMBOL	MIN.	MAX.			
А	0.70	0.80			
D	2.90	3.10			
E	2.90	3.10			
A1	0.00	0.05			
L	0.20	0.40			
k 0.25 MIN.					
A2 0.20 REF.					

PACKAGE VARIATIONS								
PKG. CODE	N	D2	E2	е	JEDEC SPEC	b	[(N/2)-1] x e	
T633-1	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF	
T833-1	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T1033-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	

NOTES:

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- ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
  COPLANARITY SHALL NOT EXCEED 0.08 mm.
  WARPAGE SHALL NOT EXCEED 0.10 mm.

- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS
- SPECIAL CHARACTERISTIC(S).
- 5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2".
- "N" IS THE TOTAL NUMBER OF LEADS. 6.

#### DALLAS PACKAGE OUTLINE, 6, 8 & 10L TDFN, EXPOSED PAD, 3x3x0.80 mm $\frac{2}{2}$ D 21-0137

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